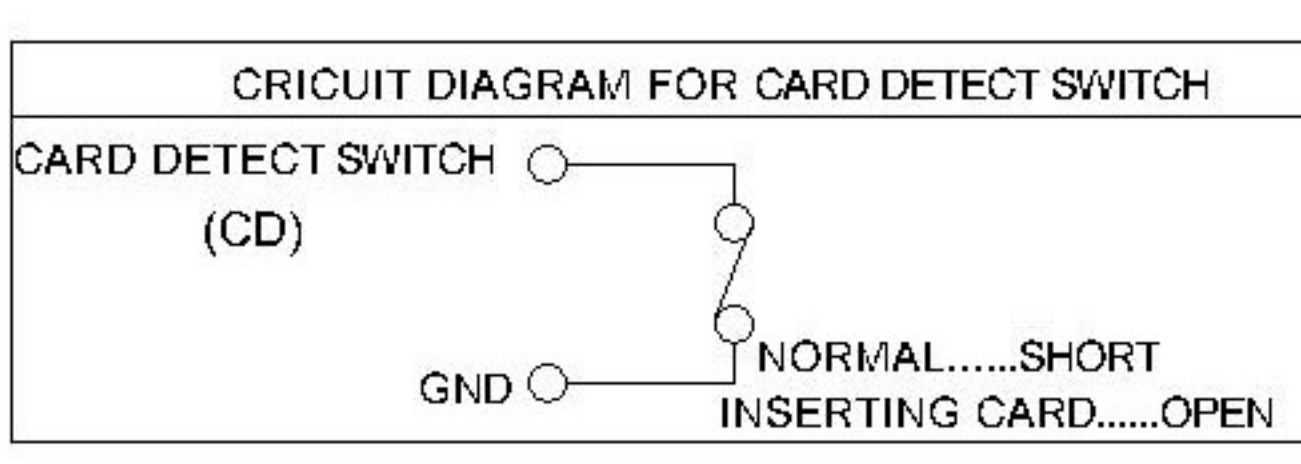


NOTES:
 1) MATERIAL:
 HOUSING: HI-TEMP. PLASIC UL 94V-0
 TERMINAL: COPPER ALLOY
 SHELL: SUS
 2) PLATING:
 TERMINAL:
 CONTACT AREA: Au GOLD FLASH.
 SOLDER AREA: AU GOLD FLASH.
 UNDER PLATE: NICKEL.
 SHELL: NICKEL PLATED OVER ALL.
 SOLDER AREA: GOLD FLASH.
 3) SPECIALITY:
 3.1 Rated current: 1.0A
 3.2 Rated voltage: 30V
 3.3 Contact Resistance: 50m Ω MAX
 3.4 Insulation Resistance: 1000M Ω MIN 500V DC
 3.5 Dielectric withstanding voltage: 500V AC.
 3.6 Solder ability: 260±0.5 °C, 30±10s.
 3.7 Durability: 5000 Cycles Min.
 3.8 Operating condition: Temperature -40 °C ~ +85 °C;
 Humidity 80% R.H MAX

RECOMMENDED PCB LAYOUT
 GENERAL TOLERANCE ±0.05



SWITCH CONNECTOR

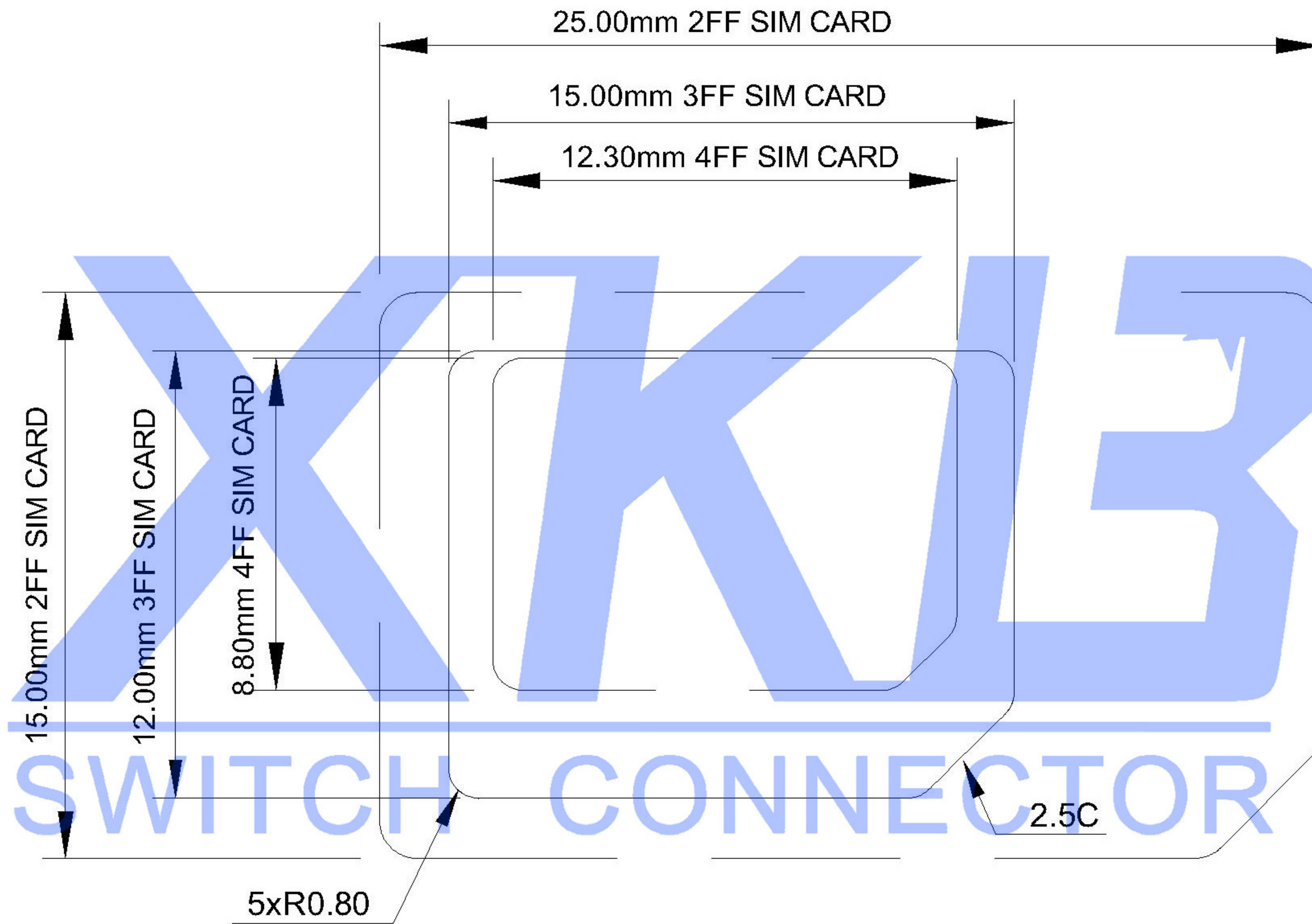


4FF SIM CARD

SIM pin Assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O

ITEM	PAPT NAMF	QTY	MATERIAL	FINISHING
③	Shell	1	SUS	
②	Terminal	7	COPPER ALLOY	
①	Housing	1	HI-TEMP.PLASIC UL 94V-0	BLACK

MARK	DESCRIPTION	DATE	REVISED	APPROVED	UNSPECIFIED TOLERANCES	DSND	DATE	SCALE: N/A	MODEL TYPE: SIM CARD CONN
ΔX					ANGLAR ±5°	DWN	DATE	VIEW:	PART NO.:
ΔX					L ≤ 4 ±0.2	CHKD	DATE	UNIT: mm	DWG NO.:
ΔX					4 < L ≤ 16 ±0.3	APPD	DATE	SIZE: A4	XKNANO-113
					16 < L ≤ 63 ±0.4				WEIGHT
					L > 63 ±0.5				SHEET
									1/1
									REVISION
									A0



						ANGLAR	±5°	DSND		DATE		SCALE: N/A	MODEL TYPE: SIM CARD CONN	
△X						L ≤ 4	±0.2	DWN		DATE		VIEW:	PART NO.:	
△X						4 < L ≤ 16	±0.3	CHKD		DATE		UNIT: mm		
△X						16 < L ≤ 63	±0.4	APPD		DATE		SIZE: A4	DWG NO.:	
MARK	DESCRIPTION	DATE	REVISED	APPROVED		L > 63	±0.5						XKNANO-113	
REVISIONS						UNSPECIFIED TOLERANCES		XKB INDUSTRIAL PRECISION CO., LIMITED				WEIGHT	SHEET	REVISION
www.xk-dg.cn www.helloxkb.com www.helloxkb.cn												1.0g	1/1	A0